# 80 mA Ultra-Low Iq, Wide Input Voltage Low Dropout Regulator

The NCP716 is 80 mA LDO Linear Voltage Regulator. It is a very stable and accurate device with ultra–low ground current consumption (4.7  $\mu$ A over the full output load range) and a wide input voltage range (up to 24 V). The regulator incorporates several protection features such as Thermal Shutdown and Current Limiting.

#### Features

- Operating Input Voltage Range: 2.5 V to 24 V
- Fixed Voltage Options Available: 1.2 V to 5.0 V
- Ultra Low Quiescent Current: Max. 4.7 µA over Temperature
- ±2% Accuracy over Full Load, Line and Temperature Variations
- PSRR: 60 dB at 100 kHz
- Noise: 200 µV<sub>RMS</sub> from 200 Hz to 100 kHz
- Thermal Shutdown and Current Limit Protection
- Available in WDFN6, 2x2x0.8 mm Package
- This is a Pb–Free Device

#### **Typical Applicaitons**

- Portable Equipment
- Communication Systems



Figure 1. Typical Application Schematic



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XX = Specific Device Code M = Date Code





#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 17 of this data sheet.



Figure 2. Simplified Block Diagram

#### **Table 1. PIN FUNCTION DESCRIPTION**

Pin No. wDFN6, 2 x 2	Pin Name	Description
6	OUT	Regulated output voltage pin. A small 0.47 $\mu\text{F}$ ceramic capacitor is needed from this pin to ground to assure stability.
2	NC/GND*	No connection at NCP716MT devices. This pin can be tied to ground to improve thermal dissipation or left disconnected. *Power supply ground at NCP716MTG devices.
3, EXP	GND	Power supply ground. Exposed pad EXP must be tied with GND pin 3.
4	N/C	No connection. This pin can be tied to ground to improve thermal dissipation or left disconnected.
5	N/C	No connection. This pin can be tied to ground to improve thermal dissipation or left disconnected.
1	IN	Input pin. A small capacitor is needed from this pin to ground to assure stability.

#### Table 2. ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage (Note 1)	V <sub>IN</sub>	-0.3 to 24	V
Output Voltage	V <sub>OUT</sub>	-0.3 to 6	V
Output Short Circuit Duration	t <sub>SC</sub>	Indefinite	S
Maximum Junction Temperature	T <sub>J(MAX)</sub>	150	°C
Operating Ambient Temperature Range	T <sub>A</sub>	-40 to 125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
ESD Capability, Human Body Model (Note 2)	ESD <sub>HBM</sub>	2000	V
ESD Capability, Machine Model (Note 2)	ESD <sub>MM</sub>	200	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.

This device series incorporates ESD protection and is tested by the following methods: ESD Human Body Model tested per EIA/JESD22–A114

- ESD Machine Model tested per EIA/JESD22-A115

ESD Charged Device Model tested per EIA/JESD22–C101E Latch up Current Maximum Rating tested per JEDEC standard: JESD78.

#### **Table 3. THERMAL CHARACTERISTICS**

Rating	Symbol	Value	Unit
Thermal Characteristics, WDFN6, 2 mm x 2 mm Thermal Resistance, Junction-to-Air	$R_{\thetaJA}$	120	°C/W

#### Table 4. ELECTRICAL CHARACTERISTICS Voltage version 1.2 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$ ;  $V_{IN} = 3.0$  V;  $I_{OUT} = 1$  mA,  $C_{IN} = C_{OUT} = 1.0 \ \mu$ F, unless otherwise noted. Typical values are at  $T_J = +25^{\circ}C$ . (Note 5)

Parameter	Test Conditions	6	Symbol	Min	Тур	Max	Unit
Operating Input Voltage	I <sub>OUT</sub> ≤ 10 mA		V <sub>IN</sub>	2.5		24	V
	10 mA < I <sub>OUT</sub> < 80 mA			3.0		24	
Output Voltage Accuracy	$3.0 \text{ V} < \text{V}_{\text{IN}} < 24 \text{ V}, 0 < \text{I}_{\text{OL}}$	<sub>JT</sub> < 80 mA	V <sub>OUT</sub>	1.164	1.2	1.236	V
Turn–On Time	I <sub>OUT</sub> = 1 mA		t <sub>ON</sub>	-	700	-	μs
Undervoltage Lock–Out	V <sub>IN</sub> rising		UVLO	-	2.1	-	V
Line Regulation	$3.0 \text{ V} \leq \text{V}_{\text{IN}} \leq 24 \text{ V}, \text{ I}_{\text{OUT}} = 1 \text{ mA}$		Reg <sub>LINE</sub>		30		mV
Load Regulation	I <sub>OUT</sub> = 0 mA to 80 mA		Reg <sub>LOAD</sub>		20		mV
Dropout voltage (Note 3)			V <sub>DO</sub>			-	mV
Maximum Output Current	(Note 6)		I <sub>OUT</sub>	110			mA
Ground current	0 < I <sub>OUT</sub> < 80 mA, -40 <	T <sub>A</sub> < 85°C	I <sub>GND</sub>		3.2	4.2	μΑ
	0 < I <sub>OUT</sub> < 80 mA, V <sub>IN</sub>	= 24 V				5.8	μΑ
Power Supply Rejection Ratio		f = 100 kHz	PSRR		63		dB
Output Noise Voltage	V <sub>OUT</sub> = 1.2 V, I <sub>OUT</sub> = 80 mA f = 200 Hz to 100 kHz		V <sub>N</sub>		105		$\mu V_{rms}$
Thermal Shutdown Temperature (Note 4)	Temperature increasing from $T_J = +25^{\circ}C$		T <sub>SD</sub>		155		°C
Thermal Shutdown Hysteresis (Note 4)	Temperature falling fro	m T <sub>SD</sub>	T <sub>SDH</sub>	-	25	-	°C

Not Characterized at V<sub>IN</sub> = 3.0 V, V<sub>OUT</sub> = 1.2 V, I<sub>OUT</sub> = 80 mA
 Guaranteed by design and characterization.
 Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at T<sub>J</sub> = T<sub>A</sub> = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

#### Table 5. ELECTRICAL CHARACTERISTICS Voltage version 1.5 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$ ;  $V_{IN} = 3.0$  V;  $I_{OUT} = 1$  mA,  $C_{IN} = C_{OUT} = 1.0 \ \mu$ F, unless otherwise noted. Typical values are at  $T_J = +25^{\circ}C$ . (Note 9)

Parameter	Test Conditions		Symbol	Min	Тур	Max	Unit
Operating Input Voltage	I <sub>OUT</sub> ≤ 10 mA		V <sub>IN</sub>	2.5		24	V
	10 mA < I <sub>OUT</sub> < 80 mA			3.0		24	
Output Voltage Accuracy	$3.0 \text{ V} < \text{V}_{\text{IN}} < 24 \text{ V}, 0 < \text{I}_{\text{OL}}$	<sub>JT</sub> < 80 mA	V <sub>OUT</sub>	1.455	1.5	1.545	V
Turn–On Time	I <sub>OUT</sub> = 1 mA		t <sub>ON</sub>	-	700	-	μs
Undervoltage Lock–Out	V <sub>IN</sub> rising		UVLO	-	2.1	-	V
Line Regulation	$3.0 \text{ V} \leq \text{V}_{\text{IN}} \leq 24 \text{ V}, \text{ I}_{\text{OUT}} = 1 \text{ mA}$		Reg <sub>LINE</sub>		20		mV
Load Regulation	I <sub>OUT</sub> = 0 mA to 80 mA		Reg <sub>LOAD</sub>		20		mV
Dropout voltage (Note 7)							
Maximum Output Current	(Note 10)		I <sub>OUT</sub>	110			mA
Ground current	0 < I <sub>OUT</sub> < 80 mA, -40 <	T <sub>A</sub> < 85°C	I <sub>GND</sub>		3.2	4.2	μΑ
	0 < I <sub>OUT</sub> < 80 mA, V <sub>IN</sub>	= 24 V				5.8	μΑ
Power Supply Rejection Ratio		f = 100 kHz	PSRR		60		dB
Output Noise Voltage	V <sub>OUT</sub> = 1.5 V, I <sub>OUT</sub> = 80 mA f = 200 Hz to 100 kHz		V <sub>N</sub>		120		$\mu V_{\text{rms}}$
Thermal Shutdown Temperature (Note 8)	Temperature increasing from T <sub>J</sub> = +25°C		T <sub>SD</sub>		155		°C
Thermal Shutdown Hysteresis (Note 8)	Temperature falling fro	m T <sub>SD</sub>	T <sub>SDH</sub>	-	25	-	°C

7. Not Characterized at V<sub>IN</sub> = 3.0 V, V<sub>OUT</sub> = 1.5 V, I<sub>OUT</sub> = 80 mA
8. Guaranteed by design and characterization.
9. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at T<sub>J</sub> = T<sub>A</sub> = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible. 10. Respect SOA

#### Table 6. ELECTRICAL CHARACTERISTICS Voltage version 1.8 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$ ;  $V_{IN} = 3.0 \text{ V}$ ;  $I_{OUT} = 1 \text{ mA}$ ,  $C_{IN} = C_{OUT} = 1.0 \mu$ F, unless otherwise noted. Typical values are at  $T_J = +25^{\circ}C$ . (Note 13)

Parameter	Test Conditions	6	Symbol	Min	Тур	Max	Unit
Operating Input Voltage	I <sub>OUT</sub> ≤ 10 mA		V <sub>IN</sub>	2.8		24	V
	10 mA < I <sub>OUT</sub> < 80	mA		3.0		24	
Output Voltage Accuracy	$3.0 \text{ V} < \text{V}_{\text{IN}} < 24 \text{ V}, 0 < \text{I}_{\text{OL}}$	<sub>JT</sub> < 80 mA	V <sub>OUT</sub>	1.746	1.8	1.854	V
Turn–On Time	I <sub>OUT</sub> = 1 mA		t <sub>ON</sub>	-	700	-	μs
Undervoltage Lock–Out	V <sub>IN</sub> rising		UVLO	-	2.1	-	V
Line Regulation	3.0 V $\leq$ V <sub>IN</sub> $\leq$ 24 V, I <sub>OUT</sub>	Reg <sub>LINE</sub>		15		mV	
Load Regulation	I <sub>OUT</sub> = 0 mA to 80 mA		Reg <sub>LOAD</sub>		15		mV
Dropout voltage (Note 11)							
Maximum Output Current	(Note 14)		I <sub>OUT</sub>	110			mA
Ground current	0 < I <sub>OUT</sub> < 80 mA, -40 <	T <sub>A</sub> < 85°C	I <sub>GND</sub>		3.2	4.2	μΑ
	0 < I <sub>OUT</sub> < 80 mA, V <sub>IN</sub>	= 24 V				5.8	μΑ
Power Supply Rejection Ratio		f = 100 kHz	PSRR		60		dB
Output Noise Voltage	V <sub>OUT</sub> = 1.8 V, I <sub>OUT</sub> = 80 mA f = 200 Hz to 100 kHz		V <sub>N</sub>		140		$\mu V_{\text{rms}}$
Thermal Shutdown Temperature (Note 12)	Temperature increasing from	n T <sub>J</sub> = +25°C	T <sub>SD</sub>		155		°C
Thermal Shutdown Hysteresis (Note 12)	Temperature falling fro	m T <sub>SD</sub>	T <sub>SDH</sub>	-	25	-	°C

11. Not Characterized at  $V_{IN} = 3.0 \text{ V}$ ,  $V_{OUT} = 1.8 \text{ V}$ ,  $I_{OUT} = 80 \text{ mA}$ 12. Guaranteed by design and characterization. 13. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at  $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

 $\begin{array}{l} \textbf{Table 7. ELECTRICAL CHARACTERISTICS Voltage version 2.5 V} \\ -40^{\circ}\text{C} \leq \text{T}_{J} \leq 125^{\circ}\text{C}; \ \text{V}_{\text{IN}} = 3.5 \ \text{V}; \ \text{I}_{\text{OUT}} = 1 \ \text{mA}, \ \text{C}_{\text{IN}} = \text{C}_{\text{OUT}} = 1.0 \ \mu\text{F}, \ \text{unless otherwise noted}. \ \text{Typical values are at } \text{T}_{J} = +25^{\circ}\text{C}. \ (\text{Note 17}) \ \text{mA}, \ \text{C}_{\text{IN}} = \text{C}_{\text{OUT}} = 1.0 \ \mu\text{F}, \ \text{unless otherwise noted}. \ \text{Typical values are at } \text{T}_{J} = +25^{\circ}\text{C}. \ (\text{Note 17}) \ \text{mA}, \ \text{C}_{\text{IN}} = 1.0 \ \mu\text{F}, \ \text{mA} = 1.0 \ \mu\text{F}, \ \text{mA}$ 

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit	
Operating Input Voltage	0 < I <sub>OUT</sub> < 80 m/	V <sub>IN</sub>	3.5		24	V	
Output Voltage Accuracy	$3.5 \text{ V} < \text{V}_{\text{IN}} < 24 \text{ V}, 0 < \text{I}_{\text{OL}}$	<sub>IT</sub> < 80 mA	V <sub>OUT</sub>	2.45	2.5	2.55	V
Turn–On Time	I <sub>OUT</sub> = 1 mA		t <sub>ON</sub>	-	700	-	μs
Undervoltage Lock–Out	V <sub>IN</sub> rising		UVLO	-	2.1	-	V
Line Regulation	$V_{OUT}$ + 1 V $\leq$ V <sub>IN</sub> $\leq$ 24 V, I	DUT = 1mA	Reg <sub>LINE</sub>		15		mV
Load Regulation	$I_{OUT} = 0 \text{ mA to } 80 \text{ mA}$		Reg <sub>LOAD</sub>		15		mV
Dropout voltage (Note 15)	$V_{DO} = V_{IN} - (V_{OUT(NOM)} - 75 \text{ mV})$ $I_{OUT} = 80 \text{ mA}$		V <sub>DO</sub>		400	640	mV
Maximum Output Current	(Note 18)		I <sub>OUT</sub>	110			mA
Ground current	0 < I <sub>OUT</sub> < 80 mA, -40 <	T <sub>A</sub> < 85°C	I <sub>GND</sub>		3.2	4.2	μΑ
	0 < I <sub>OUT</sub> < 80 mA, V <sub>IN</sub>	= 24 V				5.8	μΑ
Power Supply Rejection Ratio		f = 100 kHz	PSRR		60		dB
Output Noise Voltage	V <sub>OUT</sub> = 2.5 V, I <sub>OUT</sub> = 80 mA f = 200 Hz to 100 kHz		V <sub>N</sub>		160		μV <sub>rms</sub>
Thermal Shutdown Temperature (Note 16)	Temperature increasing from $T_J = +25^{\circ}C$		T <sub>SD</sub>		155		°C
Thermal Shutdown Hysteresis (Note 16)	Temperature falling fro	m T <sub>SD</sub>	T <sub>SDH</sub>	-	25	-	°C

15. Characterized when  $V_{OUT}$  falls 75 mV below the regulated voltage and only for devices with  $V_{OUT}$  = 2.5 V 16. Guaranteed by design and characterization.

17. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at  $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

Table 8. ELECTRICAL CHARACTERISTICS Voltage version 3.0 V $-40^{\circ}C \le T_J \le 125^{\circ}C$ ;  $V_{IN} = 4.0$  V;  $I_{OUT} = 1$  mA,  $C_{IN} = C_{OUT} = 1.0$  µF, unless otherwise noted. Typical values are at  $T_J = +25^{\circ}C$ . (Note 21)

Parameter	Test Conditions		Symbol	Min	Тур	Max	Unit
Operating Input Voltage	0 < I <sub>OUT</sub> < 80 m/	٩	V <sub>IN</sub>	4.0		24	V
Output Voltage Accuracy	$4.3 \text{ V} < \text{V}_{\text{IN}} < 24 \text{ V}, 0 < \text{I}_{\text{OL}}$	<sub>JT</sub> < 80 mA	V <sub>OUT</sub>	2.94	3.0	3.06	V
Turn–On Time	I <sub>OUT</sub> = 1 mA		t <sub>ON</sub>	-	700	-	μs
Undervoltage Lock–Out	V <sub>IN</sub> rising		UVLO	-	2.1	-	V
Line Regulation	$V_{OUT}$ + 1 V $\leq$ V <sub>IN</sub> $\leq$ 24 V, I <sub>O</sub>	<sub>DUT</sub> = 1 mA	Reg <sub>LINE</sub>		4	10	mV
Load Regulation	I <sub>OUT</sub> = 0 mA to 80 mA		Reg <sub>LOAD</sub>		10	30	mV
Dropout voltage (Note 19)	$V_{DO} = V_{IN} - (V_{OUT(NOM)} - 90 \text{ mV})$ $I_{OUT} = 80 \text{ mA}$		V <sub>DO</sub>		370	580	mV
Maximum Output Current	(Note 22)		I <sub>OUT</sub>	110			mA
Ground current	0 < I <sub>OUT</sub> < 80 mA, -40 <	T <sub>A</sub> < 85°C	I <sub>GND</sub>		3.2	4.2	μΑ
	0 < I <sub>OUT</sub> < 80 mA, V <sub>IN</sub>	= 24 V				5.8	μA
Power Supply Rejection Ratio		f = 100 kHz	PSRR		58		dB
Output Noise Voltage	V <sub>OUT</sub> = 4.3 V, I <sub>OUT</sub> = 80 mA f = 200 Hz to 100 kHz		V <sub>N</sub>		190		$\mu V_{rms}$
Thermal Shutdown Temperature (Note 20)	Temperature increasing from $T_J = +25^{\circ}C$		T <sub>SD</sub>		155		°C
Thermal Shutdown Hysteresis (Note 20)	Temperature falling fro	m T <sub>SD</sub>	T <sub>SDH</sub>	-	25	-	°C

19. Characterized when  $V_{OUT}$  falls 90 mV below the regulated voltage and only for devices with  $V_{OUT}$  = 3.0 V 20. Guaranteed by design and characterization.

21. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at  $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

 $\begin{array}{l} \textbf{Table 9. ELECTRICAL CHARACTERISTICS Voltage version 3.3 V} \\ -40^{\circ}C \leq T_J \leq 125^{\circ}C; \ V_{IN} = 4.3 \ V; \ I_{OUT} = 1 \ \text{mA}, \ C_{IN} = C_{OUT} = 1.0 \ \mu\text{F}, \ \text{unless otherwise noted}. \ \text{Typical values are at} \ T_J = +25^{\circ}C. \ (\text{Note } 25) \ \text{mathematical values} \ \text{mat$ 

Parameter	Test Conditions		Symbol	Min	Тур	Max	Unit
Operating Input Voltage	0 < I <sub>OUT</sub> < 80 m/	V <sub>IN</sub>	4.3		24	V	
Output Voltage Accuracy	$4.3 \text{ V} < \text{V}_{\text{IN}} < 24 \text{ V}, 0 < \text{I}_{\text{OL}}$	<sub>JT</sub> < 80 mA	V <sub>OUT</sub>	3.234	3.3	3.366	V
Turn–On Time	I <sub>OUT</sub> = 1 mA		t <sub>ON</sub>	-	700	-	μs
Undervoltage Lock–Out	V <sub>IN</sub> rising		UVLO	-	2.1	-	V
Line Regulation	$V_{OUT}$ + 1 V $\leq$ V <sub>IN</sub> $\leq$ 24 V, I <sub>C</sub>	<sub>DUT</sub> = 1 mA	Reg <sub>LINE</sub>		4	10	mV
Load Regulation	$I_{OUT} = 0 \text{ mA to } 80 \text{ mA}$		Reg <sub>LOAD</sub>		10	30	mV
Dropout voltage (Note 23)	$V_{DO} = V_{IN} - (V_{OUT(NOM)} - 99 \text{ mV})$ $I_{OUT} = 80 \text{ mA}$		V <sub>DO</sub>		350	560	mV
Maximum Output Current	(Note 26)		I <sub>OUT</sub>	110			mA
Ground current	0 < I <sub>OUT</sub> < 80 mA, -40 <	T <sub>A</sub> < 85°C	I <sub>GND</sub>		3.2	4.2	μΑ
	0 < I <sub>OUT</sub> < 80 mA, V <sub>IN</sub>	= 24 V				5.8	μΑ
Power Supply Rejection Ratio		f = 100 kHz	PSRR		60		dB
Output Noise Voltage	V <sub>OUT</sub> = 4.3 V, I <sub>OUT</sub> = 80 mA f = 200 Hz to 100 kHz		V <sub>N</sub>		200		$\mu V_{\text{rms}}$
Thermal Shutdown Temperature (Note 24)	Temperature increasing from $T_J = +25^{\circ}C$		T <sub>SD</sub>		155		°C
Thermal Shutdown Hysteresis (Note 24)	Temperature falling fro	m T <sub>SD</sub>	T <sub>SDH</sub>	-	25	-	°C

23. Characterized when  $V_{OUT}$  falls 99 mV below the regulated voltage and only for devices with  $V_{OUT}$  = 3.3 V 24. Guaranteed by design and characterization.

25. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at  $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible. 26. Respect SOA

 $\begin{array}{l} \textbf{Table 10. ELECTRICAL CHARACTERISTICS Voltage version 5.0 V} \\ -40^{\circ}C \leq T_J \leq 125^{\circ}C; \ V_{IN} = 6.0 \ V; \ I_{OUT} = 1 \ \text{mA}, \ C_{IN} = C_{OUT} = 1.0 \ \mu\text{F}, \ \text{unless otherwise noted}. \ \text{Typical values are at} \ T_J = +25^{\circ}C. \ (\text{Note 29}) \ \text{matrix} \ T_J = +25^{\circ}C. \ \text{matrix}$ 

Parameter	Test Conditions		Symbol	Min	Тур	Мах	Unit
Operating Input Voltage	0 < I <sub>OUT</sub> < 80 m/	V <sub>IN</sub>	6.0		24	V	
Output Voltage Accuracy	$6.0 \text{ V} < \text{V}_{\text{IN}} < 24 \text{ V}, 0 < \text{I}_{\text{OL}}$	<sub>JT</sub> < 80 mA	V <sub>OUT</sub>	4.9	5.0	5.1	V
Turn–On Time	I <sub>OUT</sub> = 1 mA		t <sub>ON</sub>	-	700	-	μs
Undervoltage Lock–Out	V <sub>IN</sub> rising		UVLO	-	2.1	-	V
Line Regulation	$V_{OUT}$ + 1 V $\leq$ V <sub>IN</sub> $\leq$ 24 V, I <sub>0</sub>	<sub>DUT</sub> = 1 mA	Reg <sub>LINE</sub>		4	10	mV
Load Regulation	I <sub>OUT</sub> = 0 mA to 80 mA		Reg <sub>LOAD</sub>		10	30	mV
Dropout voltage (Note 27)	$V_{DO} = V_{IN} - (V_{OUT(NOM)} - 150 \text{ mV})$ $I_{OUT} = 80 \text{ mA}$		V <sub>DO</sub>		310	500	mV
Maximum Output Current	(Note 30)		I <sub>OUT</sub>	110			mA
Ground current	0 < I <sub>OUT</sub> < 80 mA, -40 <	T <sub>A</sub> < 85°C	I <sub>GND</sub>		3.2	4.2	μA
	0 < I <sub>OUT</sub> < 80 mA, V <sub>IN</sub>	= 24 V				5.8	μA
Power Supply Rejection Ratio		f = 100 kHz	PSRR		54		dB
Output Noise Voltage	V <sub>OUT</sub> = 5.0 V, I <sub>OUT</sub> = 80 mA f = 200 Hz to 100 kHz		V <sub>N</sub>		220		$\mu V_{\text{rms}}$
Thermal Shutdown Temperature (Note 28)	Temperature increasing from $T_J = +25^{\circ}C$		T <sub>SD</sub>		155		°C
Thermal Shutdown Hysteresis (Note 28)	Temperature falling fro	m T <sub>SD</sub>	T <sub>SDH</sub>	_	25	_	°C

27. Characterized when  $V_{OUT}$  falls 150 mV below the regulated voltage and only for devices with  $V_{OUT}$  = 5.0 V 28. Guaranteed by design and characterization.

29. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at  $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible. 30. Respect SOA

















Figure 29. NCP716x50xxx Output Spectral Noise Density vs. Frequency



Figure 31. Load Transient Response



Figure 28. NCP716x33xxx Output Spectral Noise Density vs. Frequency







Figure 32. Load Transient Response



Figure 33. Load Transient Response



Figure 34. Line Transient Response







Figure 36. Line Transient Response



Figure 37. Line Transient Response





Figure 38. Input Voltage Turn-On Response



Figure 39. Input Voltage Turn-On Response





#### **APPLICATIONS INFORMATION**

The NCP716 is the member of new family of Wide Input Voltage Range Low Dropout Regulators which delivers Ultra Low Ground Current consumption, Good Noise and Power Supply Rejection Ratio Performance.

#### Input Decoupling (CIN)

It is recommended to connect at least 0.1  $\mu$ F Ceramic X5R or X7R capacitor between IN and GND pin of the device. This capacitor will provide a low impedance path for any unwanted AC signals or Noise superimposed onto constant Input Voltage. The good input capacitor will limit the influence of input trace inductances and source resistance during sudden load current changes.

Higher capacitance and lower ESR Capacitors will improve the overall line transient response.

#### **Output Decoupling (COUT)**

The NCP716 does not require a minimum Equivalent Series Resistance (ESR) for the output capacitor. The device is designed to be stable with standard ceramics capacitors with values of  $0.47 \,\mu\text{F}$  or greater up to  $10 \,\mu\text{F}$ . The X5R and X7R types have the lowest capacitance variations over temperature thus they are recommended.

#### Power Dissipation and Heat sinking

The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and the ambient temperature affect the rate of junction temperature rise for the part. The maximum power dissipation the NCP716 can handle is given by:

$$P_{D(MAX)} = \frac{\left[T_{J(MAX)} - T_{A}\right]}{R_{\theta JA}}$$
 (eq. 1)

The power dissipated by the NCP716 for given application conditions can be calculated from the following equations:

$$P_{D} \approx V_{IN} (I_{OND} (I_{OUT})) + I_{OUT} (V_{IN} - V_{OUT}) \quad (eq. 2)$$

or

$$V_{\text{IN(MAX)}} \approx \frac{\text{P}_{\text{D(MAX)}} + \left( \text{V}_{\text{OUT}} \times \text{I}_{\text{OUT}} \right)}{\text{I}_{\text{OUT}} + \text{I}_{\text{GND}}} \qquad (\text{eq. 3})$$

For reliable operation, junction temperature should be limited to  $+125^{\circ}$ C maximum.

#### Hints

VIN and GND printed circuit board traces should be as wide as possible. When the impedance of these traces is high, there is a chance to pick up noise or cause the regulator to malfunction. Place external components, especially the output capacitor, as close as possible to the NCP716, and make traces as short as possible.

Device	Voltage Option	Marking	Package	Shipping <sup>†</sup>
NCP716MT12TBG	1.2 V	6A		
NCP716MT15TG	1.5 V	6C		
NCP716MT18TBG	1.8 V	6D		
NCP716MT25TBG	2.5 V	6E	WDFN6	
NCP716MT30TBG	3.0 V	6F	(Pb-Free)	3000 / Tape & Reel
NCP716MT33TBG	3.3 V	6G		
NCP716MT50TBG	5.0 V	6H	7	
NCP716MTG50TBG	5.0 V	GH		

ORDERING INFORMATION

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

WDFN6 2x2, 0.65P CASE 511BR **ISSUE B** 



- DIMENSIONING AND TOLERANCING PER ASME

- THE TERMINAL TIP: COPLANARTY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS. FOR DEVICES CONTAINING WETTABLE FLANK OPTION, DETAIL A ALTERNATE CONSTRUCTION A-2 AND DETAIL A BLITERNATE CONSTRUCTION B A ADD FUT ADDI/CORLET
- **B-2 ARE NOT APPLICABLE**

	MILLIM	ETERS			
DIM	MIN	MAX			
Α	0.70	0.80			
A1	0.00	0.05			
A3	0.20 REF				
b	0.25	0.35			
D	2.00	BSC			
D2	1.50	1.70			
E	2.00	BSC			
E2	0.90	1.10			
е	0.65 BSC				
L	0.20	0.40			
L1		0.15			



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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